PRODUCTION SPECIFICATIONS

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TRIM SIZE: 259mm w x 55mm h STOCK: 10 pt card stock, coated, no adhesive FINISHED SIZE: Approx. 59mm w x 55mm h IN HOUSE PRINTING CAPABILITY: NO

FP 00766

BLEED: NO INKS: PMS Red(032) & Black # OF FOLDS: 2 VARNISH: yes

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Magenta die cut line for shape only does not print Cyan for imprint only does not print

Indications for use: Pors-on plus is a noble, micro-fine grain porcelain alloy, which may be used with most commercial dental porcelains. The well balanced formulation of this	Technic	al Dat	a ¹ L	Lot #					Dental Ceramic Pd: 47.5% Allow NOBLE Meight	
palladium-gold-silver alloy provides excellent tarnish and corrosion resistance significantly. Pors-on Plus features excellent physical properties and is suitable for bridges of any length.	Melting range	CTE-ran 25–500 °C 77–932 °F	ge (WAK) 25–600 °C 77–1112 °F	Vickers hardness HV5	Tensile strength* MPa	0.2% Yield strength* MPa	Elon- gation [*] %	Density g/cm ³	Anov Au: 15.5% Au: 15.5% Au: 15.5% Au: 15.5% Au: Au: </td	
Contraindications: None known.	1170-1255 °C	14.6	14.9	f: 250	f: 760	f: 445	s: 25	12.0	US Reference No. 155055 Micro-Fine Grain Alloy	
Warning: Exposure to alloy dust or fumes may cause eye irritation ventilate work area when processing this alloy.	2140-2290 °F h: 250 h: 880 h: 605 h: 15							Pore-on™ Plue		
Precautions: Use proper safety equipment and a certified industrially ventilate work area when processing this alloy.	To convert from MPa to psi, multiply by 145 Tensile strength tests performed in accordance with ISO 9693								FUIS-UII FIUS Manufactured for:	
Adverse Reactions: Exposure to alloy dust or fumes may cause eye irritation and/or respiratory complications.	Burnout Temperature: 1650 °F (900 °C); Casting Temperature: 2550 °F (1400 °C). Dentsply International Pre-Solder: YPG or Degudent G-1; Flux: DS-1. g DENTSPLY Ceramoo Post-solder: Regular White or Degudent 2 Solder; Flux: T-Flux or DS-1. g DENTSPLY Ceramoo									
Additional information is available on request.	1 Technical Data for	š York, PA 17405-0872 Technical Data for reference only. RMC# 743-944 Rev. 02/11 RMC# 743-944 Rev. 02/11 1,277,602,4100								
For dental use only.	A See Reverse Side for Working Instructions!									

Pors-on Plus

Instructions for use

Step by Step Instructions:

1. Design:

The minimum crown wall thickness should be 0.3mm for single crowns and 0.5mm for bridge abutment crowns.

2. Sprues:

Single Crowns: Sprue directly onto the thickest part of the pattern using 8 or 6 gauge (3.5–4.0 mm diam.) sprues, 10–15 mm in length.

Bridgework: Attach 8 or 6 gauge (3.5–4.0 mm diam.) sprues to wax pattern. Connect the sprued patterns to a 6 or 4 gauge (4.0–5.0 mm diam.) runner bar, measuring the length of the bridge span. Use several 8 or 6 gauge sprues from the runner bar to the crucible cone former.

3. Investment:

Use phosphate or silicate-bound investments; for example Deguvest® F.

4. Wax Elimination

At 600 °F (315 °C) until wax is completely eliminated.

5. Burnout:

Heat to 1650 °F (900 °C) and heat-soak for 20–60 minutes depending on size of ring. More time is required with additional rings.

6. Casting:

Casting temperature: 2550 °F (1400 °C). **Do not use carbon crucibles**. When torch melting continue heating for additional 5–10 seconds (for electric melting use 20-40 seconds). After casting, allow ring to **BENCH COOL** to room temperature. Use at least 50% new alloy! Verflux® may be used to reduce oxide formation during melting.

7. Finishing:

Use only carbide burs and ceramic bound stones. Sandblast with non-recyclable aluminum oxide 110 microns and clean thoroughly.

8. Degassing:

Degas at 1800 °F (980 °C) without vacuum and hold for 5 minutes. Sandblast with non-recyclable aluminum oxide, 110-150 microns at 28 psi. Clean thoroughly.

9. Porcelain Application:

Follow manufacturer's instructions. To enhance the bonding properties the opaque should be fired in two layers. Apply the first layer very thin and the second layer to normal thickness. To harden following porcelial ring, heat to 1200 °F (650 °C), hold for 15 minutes and cool in air.

10. Pre-Soldering:

YPG 1950 °F (1065 °C) or Degudent G 1 1886 °F (1030 °C); Flux: DS 1.

11. Post-Soldering:

Use Regular White, 1365 °F (740 °C) or Degulor® 2 Solder, 1382 °F (750 °C). Flux: T-Flux or DS-1.